

Report from WP13 Prospective and Technology-driven Detector R&D

AIDAInnova Annual Meeting, April 25, 2023
ADEIT and CSIC, Valencia (Spain)

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- **Thin Silicon Sensors for Extreme Fluences**

Make Si sensors radiation tolerant by using a thin bulk, internal amplification and using a gain implant that would withstand a factor of 50 higher fluences than what is presently available

- **The Silicon Electron Multiplier, a new approach to charge multiplication in solid state detectors**

Make Si sensors radiation tolerant by a novel biasing method – electrodes embedded in silicon

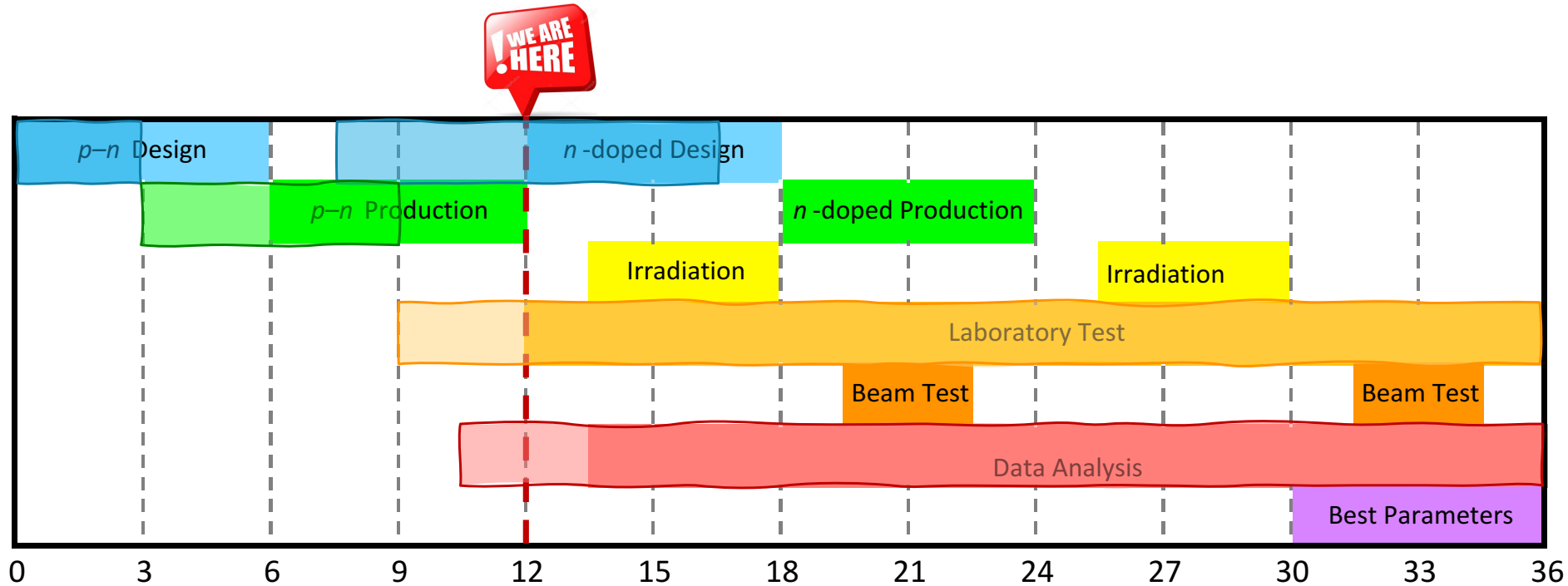
- **Development of fine-sampling calorimeters with nanocomposite scintillating materials**

Develop a new generation of fine-sampling calorimeters that use innovative scintillating materials based on perovskite nanocrystals dispersed in a plastic matrix to form fast ($\sim 100\text{ps}$) and radiation resistant ($\sim 1\text{ MGy}$) scintillators

- **Wireless Data Transfer for High-Energy Physics Applications**

Develop mm-wave-based wireless communication as an alternative to optical and wired links in a HEP-like environment to reduce the material and optimize the read-out

eXFlu-innova – Project Plan



Deliverables:

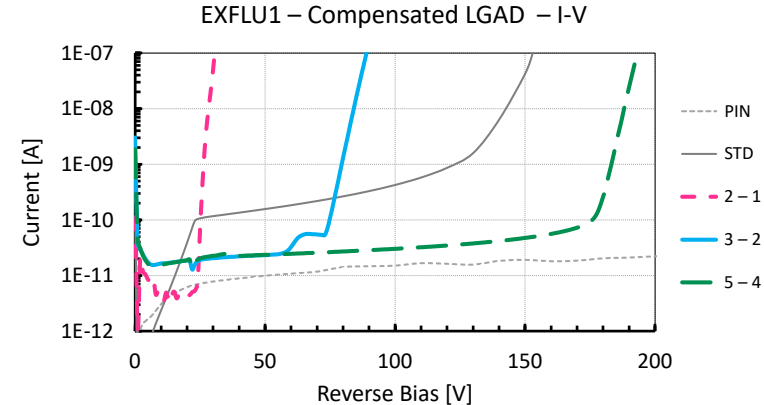
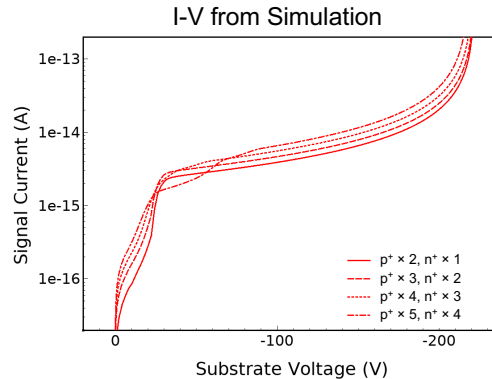
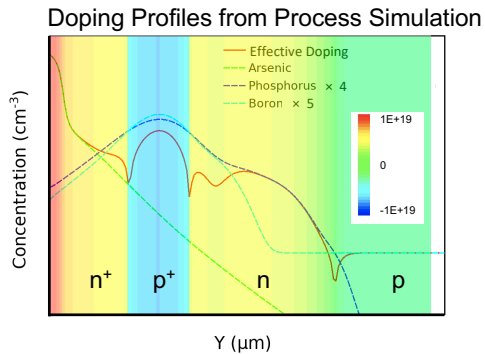
1. **simulation and design** of the $p-n$ compensated gain implant (M6) – DONE
2. **production** of $p-n$ compensated sensors (M12) – DONE and n -doped sensors (M24) –
3. **identifications of the best parameters** to manufacture compensated LGADs (M36) – pending



The first $p-n$ compensated LGAD



The first $p-n$ compensated LGAD production batch released in November 2022

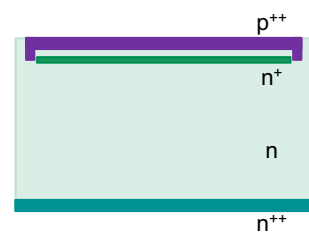


Ongoing testing on the $p-n$ compensated LGAD batch:

- I-V, C-V & test structure characterisation
- TCT scan as a function of bias voltage using different laser wavelengths
- TCT scan over the sensor surface to investigate the peripheral region of the gain implant
- SIMS on the gain implants to investigate the boron and phosphorus profiles
- preparation of the irradiation campaign

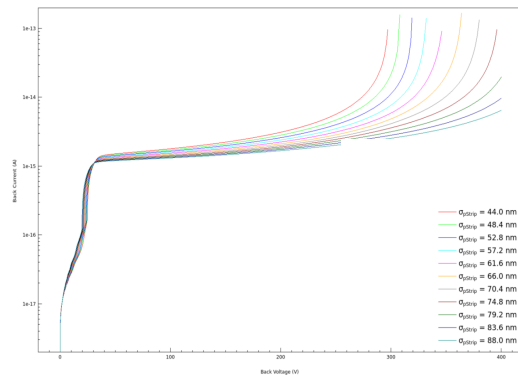
Outside eXFlu-innova: HPK presented a $p-n$ compensated LGAD batch @ TREDI2023 [\[link\]](#)

p-in-n LGAD

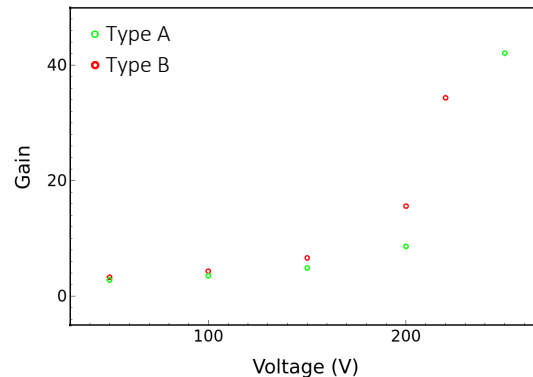


The **p-in-n LGAD** production batch is necessary to study the donor removal coefficient

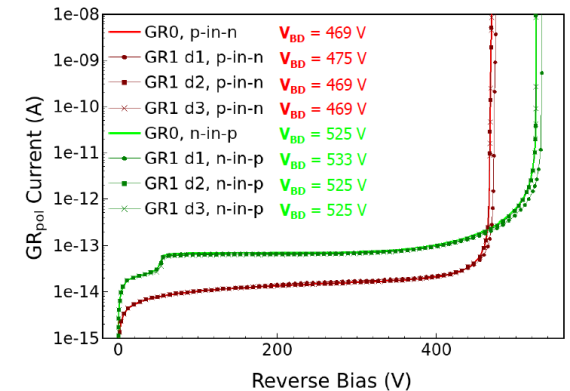
I-V simulation for different p⁺⁺ contacts



Gain simulation for different n⁺ designs



Simulation of different guard-ring structures



Ongoing simulation of the p-in-n LGAD batch:

- simulation of the electrostatic behaviour for different designs of the p⁺⁺ contact
- simulation of the transient behaviour for different designs of the n⁺ gain implant
- simulation of the electrostatic behaviour for different guard-ring designs optimised for thin substrates
- short-loop run to define the p⁺⁺ contact process parameters

Outside eXFlu-innova: CNM presented a p-in-n NLGAD batch @ 41st RD50 [\[link\]](#)

Silicon Electron Multiplier demonstrator

- Project lead by CERN and CNM
- Aim at demonstrating the concept of SiEM described in [NIM A 1041 \[2022\] 167325](#)

⇒ try to achieve gain in Si sensor with difference of potential applied to embedded electrodes rather than doping

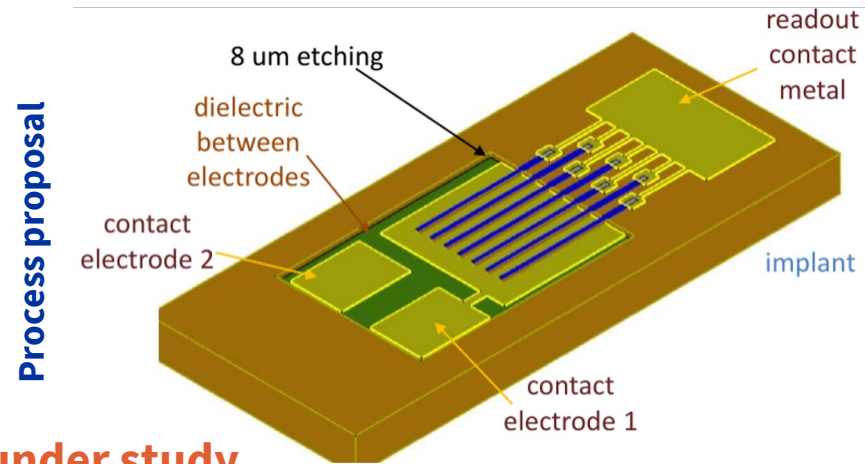
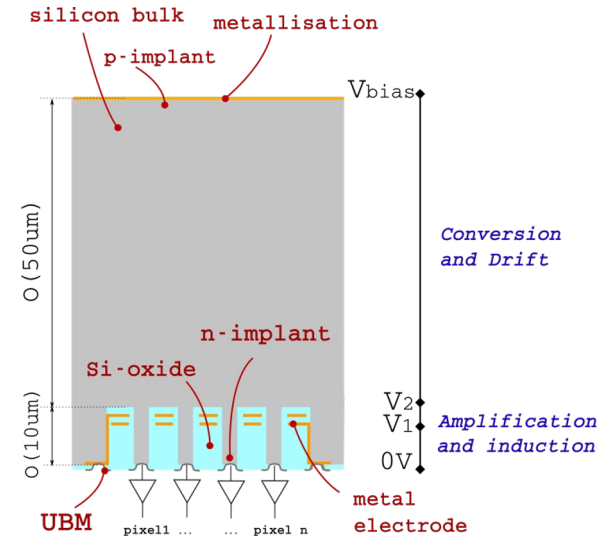
- Project organised in several phases

- [1] Definition of the process (technics, material, etc...)
- [2] TCAD simulation and design of the chosen process
- [3] Production
- [4] Characterisation
- [5] Investigation of alternative approach (different available tech., materials)

- Proposed process based on DRIE

- Process defined in second half of 2022
- Photolithography for etching pattern
- Deep reactive ion etching
- Metallisation and oxide deposition

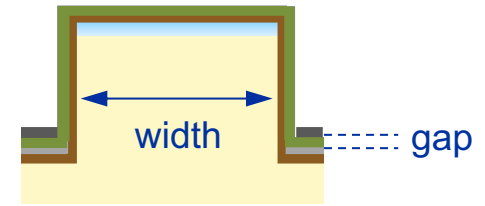
⇒ Limits and constraints of the process under study



Process proposal

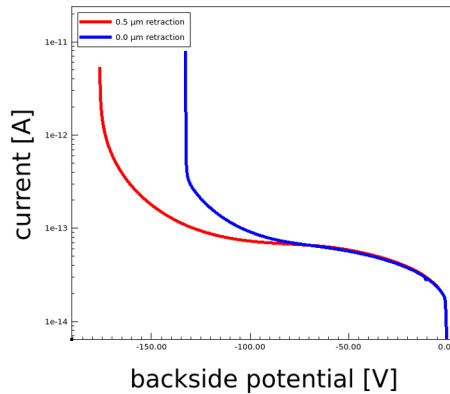
Geometry study

- **Generic interplay between geometrical parameters studied in [NIM A 1041 \[2022\] 167325](#)**
- **Geometry adapted to the real production process**
- **Specific geometrical constraints**
 - width of the amplification pillar
 - gap between amplification electrodes
 - distance between pillar and electrodes
- **Study with TCAD simulation of geometry compatible with process**
 - IV used to check if amplification happens before breakdown (checked with transient sim.)
 - best for low width and high gap
 - width limited by lithography and gap limited by oxide deposition
 - retraction of the electrode from the pillar still allow amplification (see next slide)

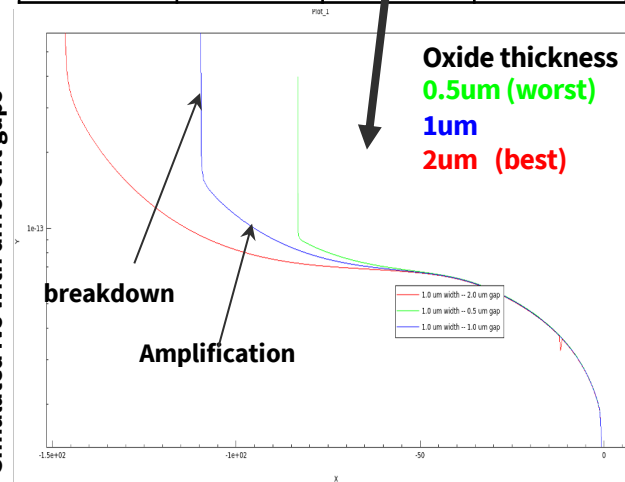


	gap: 0.5 μm	gap: 1 μm	gap: 2 μm
width: 1 μm			
width: 2 μm			
width: 3 μm			
width: 4 μm			

Simulated IVs with different electrode retraction

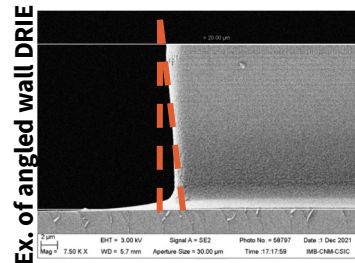


Simulated IVs with different gaps

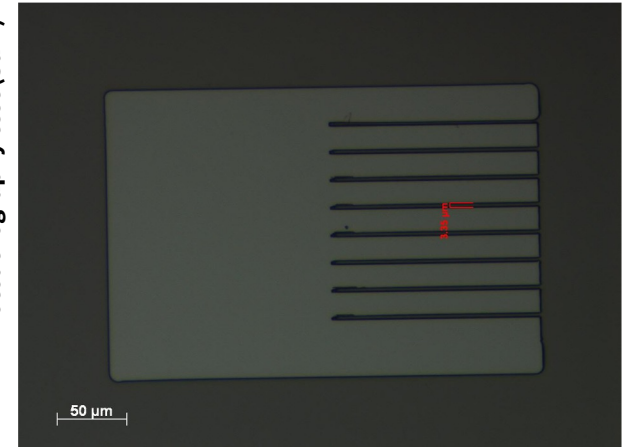


Process definition and test

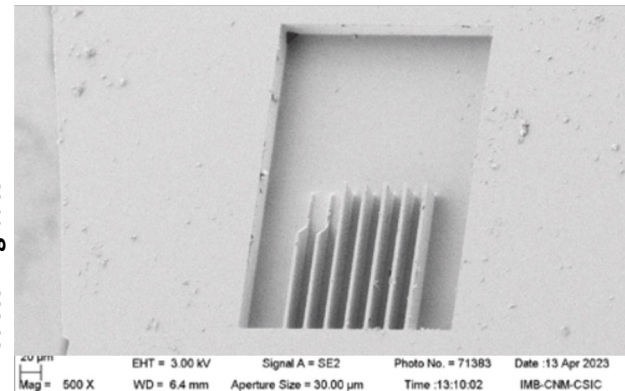
- **Test of photolithography procedure for etching**
 - 2,3,4 μ m achieved
- **1 μ m at the limit of what can be done with photolithography**
 - use e-beam lithography (prefer to avoid for demonstrator)
 - inverted pyramid geometry (ie. 1 μ m at the bottom with slanted walls)
⇒ impact is that electrodes are retracted from the pillar wall by the pyramid shadow (OK in simulation)
- **First test of the DRIE step**
 - over-etching to be corrected in the next batch (25 μ m instead of 8 μ m)
 - measurement to qualify the angle of the inverted pyramid wall on-going
- **Preparing next step**
 - metallisation and oxide deposition



Photolithography test (3 μ m)

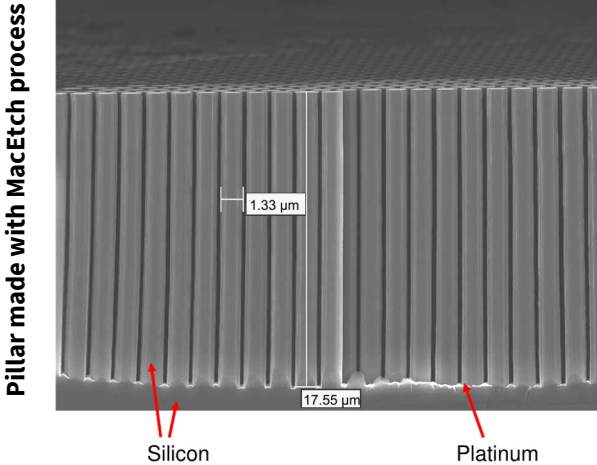


First etching batch



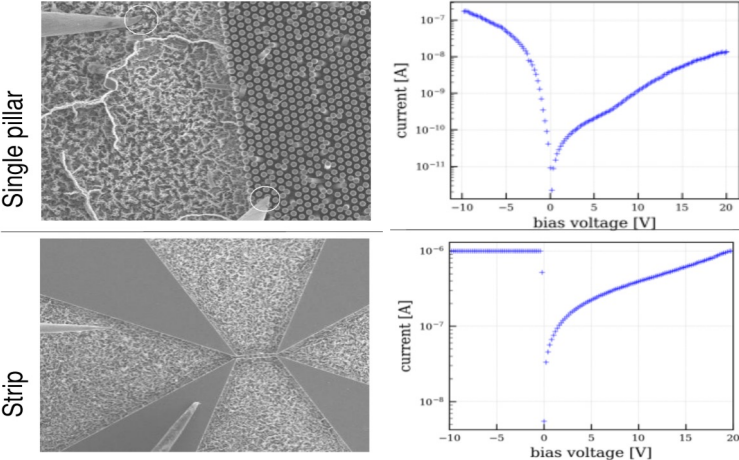
Alternative approach to SiEM

- **Study possible use of Metal assisted etching [5]**
 - parallel project between CERN and PSI, based on AdEM 22 (2020) 2000258
 - very different process constraints (cheap, high aspect ratio, first electrode deposited while etching), but never used in active device
- **Testing the structures**
 - IV just after production with probe-station \Rightarrow pn junction conserved
 - bonding of test structures for IV in the lab
 - preparing setup for laser/ source test.

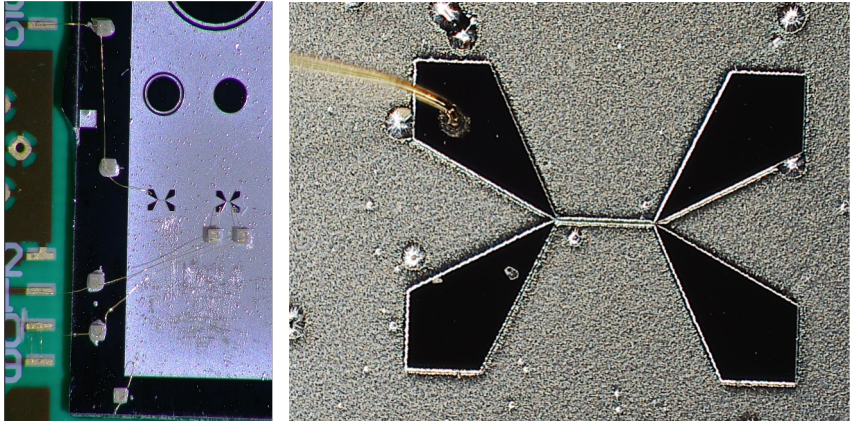


see M. Halvorsen @ RD50 41st workshop

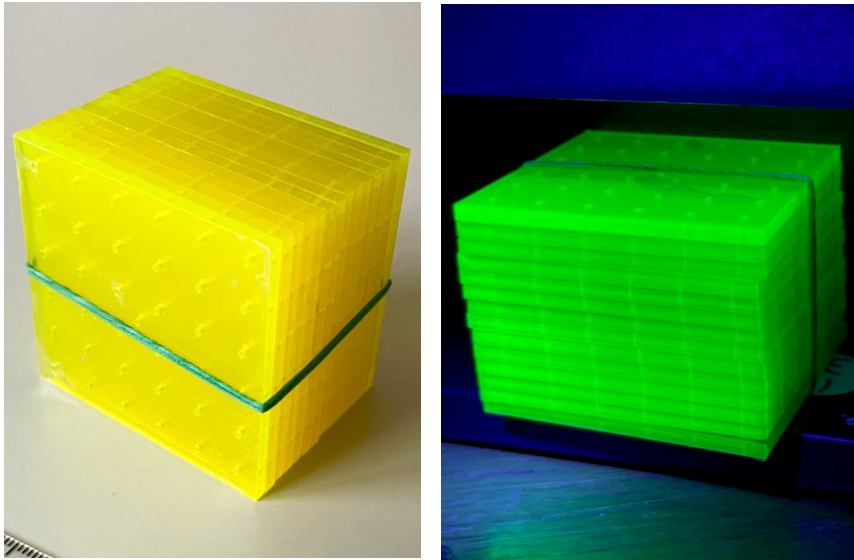
IV measured under SEM after prod.



Strip structure bonded for testing



Nanomaterial composites (NCs)



Semiconductor nanostructures can be used as sensitizers/emitters for ultrafast, robust scintillators:

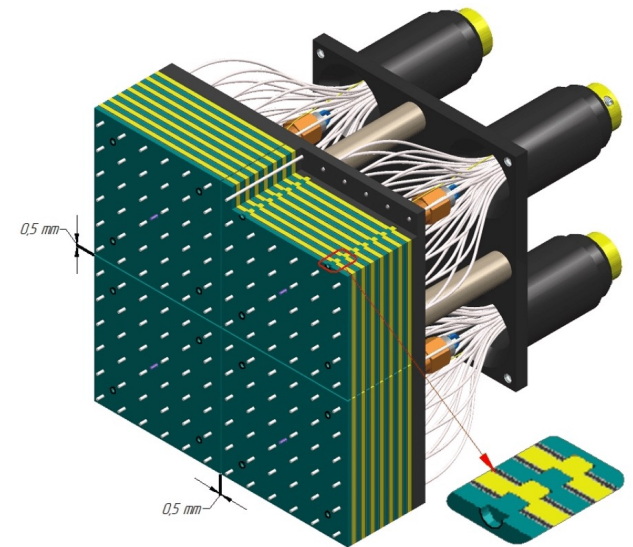
- Perovskite (ABX_3) or chalcogenide (oxide, sulfide) nanocrystals
- Cast with polymer or glass matrix
- Decay times down to $O(100 \text{ ps})$
- Radiation hard to $O(1 \text{ MGy})$

Despite promise, **applications in HEP have received little attention to date**

No attempt yet to build a **real calorimeter with NC scintillator** and **test it with high-energy beams**

Shashlyk design naturally ideal as a test platform:

- Easy to construct a shashlyk calorimeter with very fine sampling
- Primary scintillator and WLS materials required: both can be optimized using NC technology

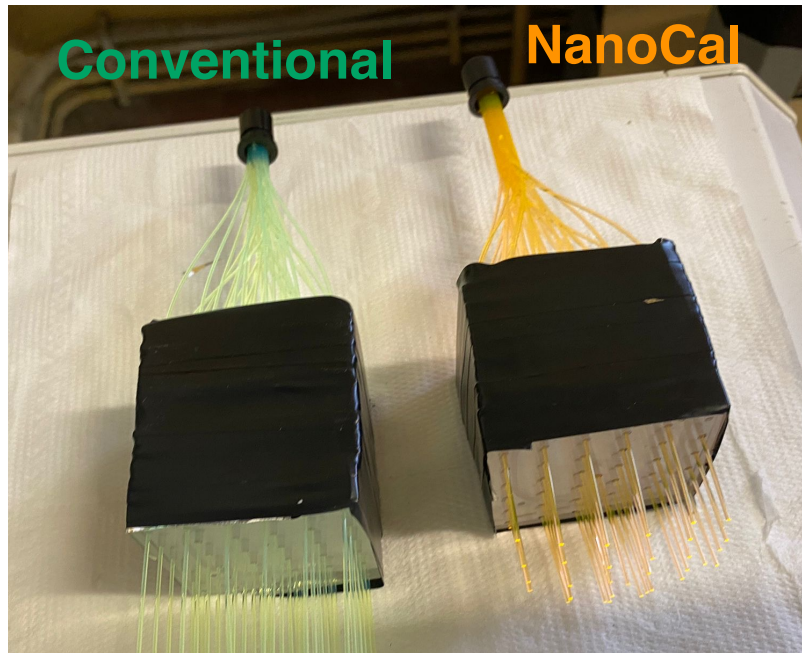


KOPIO/PANDA design
Fine-sampling shashlyk

NanoCal project status

Schedule:

- **Oct 2022: First shashlyk component test at CERN: fibers/tiles/SiPMs**
- **2023:** Further iterations to improve performance of NC scintillator prototype
- **2024:** Construction of full-scale shashlyk modules; performance comparison

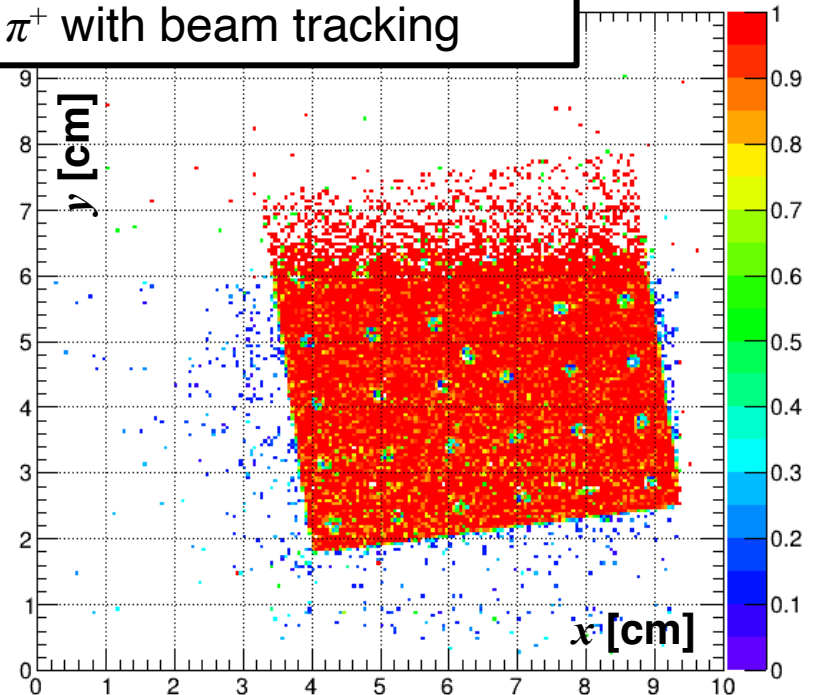


2 prototypes with 12 fine sampling layers
1.3 X_0 in depth: MIP deposit = 10 MeV

Known formulation for NC scintillator:

- 0.2% CsPbBr₃ in UV-cured PMMA
- 50% of light emitted with $\tau < 0.5$ ns

Oct 2022 test: SPS H2 beamline
 e^- and π^+ with beam tracking



Conclusion of 2022 test:

NC prototype seems to work but with low light yield and many open questions

NanoCal goals for 2023

Big effort in 2022 to test first prototype only 5 months after project start!

Beam test results ambiguous due to construction errors for NC prototype

2023 NanoCal beam test
14-21 July, T9 at CERN PS
 e^- and MIPs, 1-10 GeV

Comprehensive test program for 2023, prototypes under construction:

Conventional scintillator

Nanocal scintillator, 0.2% (rebuilt)

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Re-establish quantitative baseline with errors corrected

Nanocal scintillator, 0.2% + custom fibers

New fiber developed with Kuraray specifically optimized for CsPbBr₃ emitter: fast de-excitation, high Stokes shift

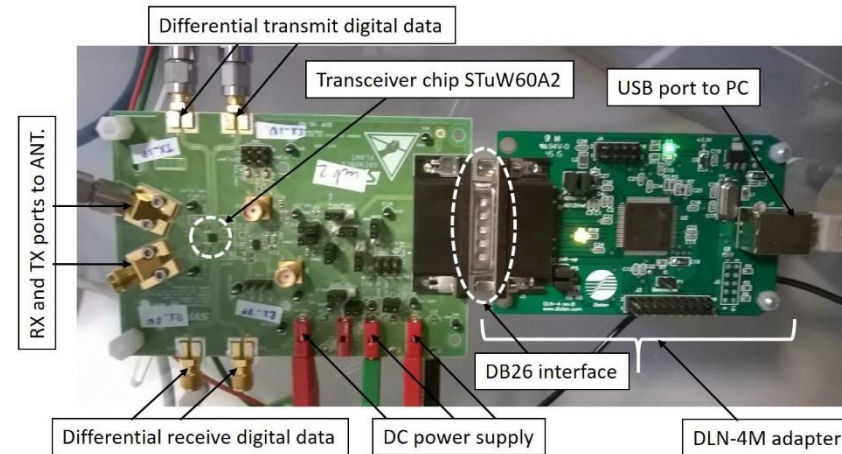
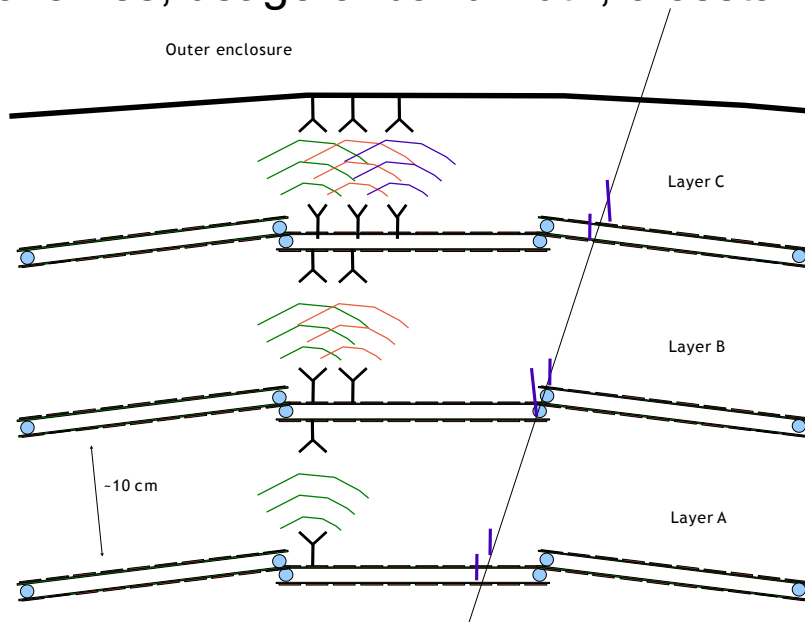
High concentration (0.8%?) + custom fibers

Test improvement in light yield with increased concentration

New formulation with CsPbCl₃ + intermediate WLS dye

Test improvement in light yield with increased absorption length

- Study of components and antennas integration
- Full link demonstrator(s) from 1 tile to 2 and 3 tiles – several mock-ups to be tested
- Use and integrate commercially available components
- Study the performance of the system (data rate, bit error rate, modulation schemes, usage of bandwidth, crosstalk in repeater, etc.)



Debit 1 Gbps per layer and is cumulative, thus it will be reaching 3 Gbps at the outer enclosure.

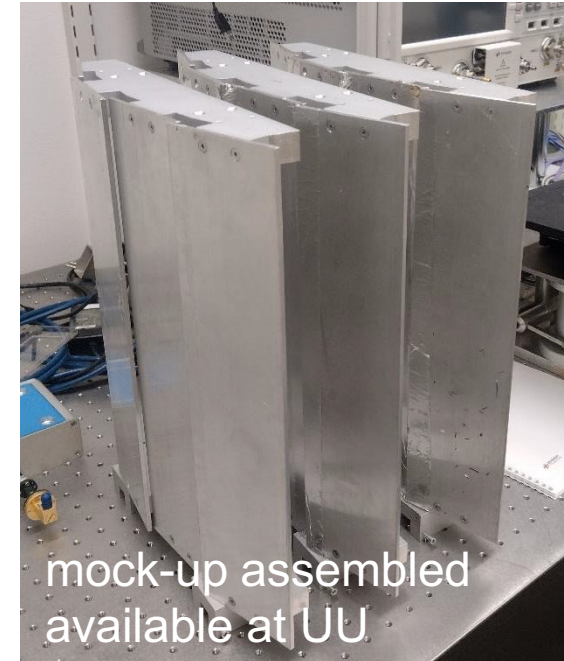
Courtesy of CEA-Letti and STMicroelectronics

Deliverable 1: First mock-up assembled and tested during the first year, including study of antenna technologies allowing a seamless integration in such a harsh environment (strong irradiation and magnetic fields); specification of the antennas.

Deliverable 2: Second mock-up assembled and tested during the two next years. Three or four layers of silicon detector with their readout, equipped with low power consumption transceiver and antennas.

Deliverable 3: Published study of performance in HEP environment and access to technology for new user communities. Make packages available with user support.

Deliverable 4: (in option depending on the time left) Study of the cumulative noise in multi-hop data transmission and jitter, development of wireless communications strategies for managing crosstalk



Summary and outlook

- The four projects are up and running
- They report at each annual meeting
- MS51: projects selection Dec 2021
MS52: midterm review Dec 2022
- A final written report is due 2 months before the end of AIDAinnova
It is expected to include an evaluation of the potential of the studied technologies, which takes into account the results of the project